# **Teccor® brand Protection Thyristors Axial Leaded**

# **ROHS DO-41 Series SIDACtor® Device**





## **Agency Approvals**

Agency

Agency File Number



E133083

#### **Description**

This DO-41 plastic package provides a through-hole version of the SIDACtor® devices. This axial leaded device is ideal for Customer Premises Equipment (CPE) such as telephones, answering machines, modems, and fax interfaces. The DO-41 package series can also be used for overvoltage protection for applications such as T1/E1/J1 trunk cards when the appropriate overcurrent protection is included.

#### **Features**

- RoHS compliant
- Bidirectional transient voltage protection
- Axial lead through-hole component
- Teccor brand SIDACtor technology

#### **Protection solution to meet**

- YD/T 950
- IEC 61000-4-5
- YD/T 993
- ITU K.20/21 Basic Level • TIA-968-A Type B Surges
- YD/T 1082
- GR 1089 Intra-building

### **Electrical Characteristics**

Part Number	Marking	V <sub>DRM</sub> @I <sub>DRM</sub> =5µA	V <sub>s</sub> @100V/μs	I <sub>H</sub>	I <sub>s</sub>	l <sub>T</sub>	V <sub>⊤</sub> @I <sub>⊤</sub> =1 amp	Capacitance @1MHz, 2V bias
		Volts	Volts	mAmps	mAmps	Amps	Volts	pF
		Min	Max	Min	Max	Max	Max	Typical
P1100THLRP	P11H	90	130	150	800	1.0	5	60
P1300THLRP	P13H	120	160	150	800	1.0	5	40
P1500THLRP	P15H	140	180	150	800	1.0	5	40
P1800THLRP	P18H	170	220	150	800	1.0	5	40
P2300THLRP	P23H	190	260	150	800	1.0	5	30
P2600THLRP	P26H	220	300	150	800	1.0	5	30
P3100THLRP	P31H	275	350	150	800	1.0	5	30
P3500THLRP	P35H	320	400	150	800	1.0	5	30

<sup>•</sup> All measurements are made at an ambient temperature of 25°C.

<sup>•</sup> Listed SIDACtor devices are bidirectional. All electrical parameters and surge ratings apply to forward and reverse polarities.

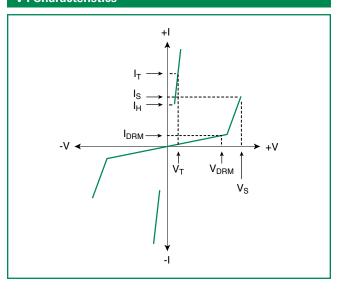


## **Surge Ratings**

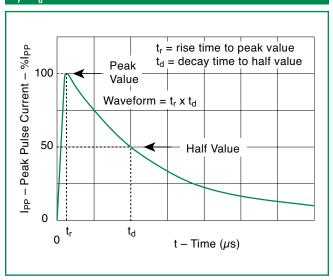
	l <sub>pp</sub>			
Series	5x320 μs	10x1000 µs		
	Amps	Amps		
	Min	Min		
Н	25	35		

- I<sub>pp</sub> applies to -40°C through +85°C temperature range.
- Ipp is a repetitive surge rating and is guaranteed for the life of the product.

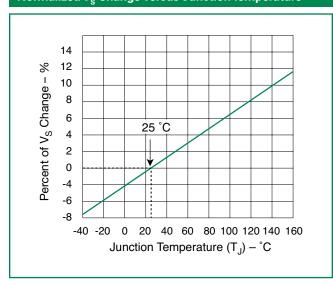
## **V-I Characteristics**



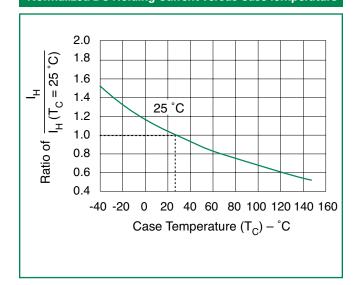
# t, x t, Pulse Waveform



# Normalized V<sub>s</sub> Change Versus Junction Temperature



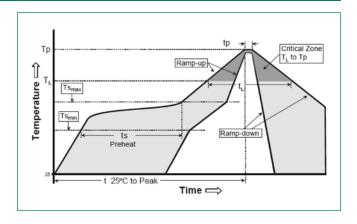
## Normalized DC Holding Current Versus Case Temperature





## **Soldering Parameters**

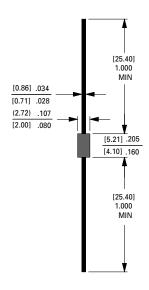
Reflow Condition		Pb – Free assembly	
Pre Heat	-Temperature Min (T <sub>s(min)</sub> )	150°C	
	-Temperature Max (T <sub>s(max)</sub> )	190°C	
	-Time (min to max) (t <sub>s</sub> )	50 - 150 seconds	
Average ramp up rate (Liquidus Temp (T <sub>L</sub> ) to peak)		5°C/second max	
$T_{S(max)}$ to $T_L$ - Ramp-up Rate		5°C/second max	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	220°C	
	-Time (min to max) (t <sub>s</sub> )	>60 - <150 seconds	
PeakTemperature (T <sub>P</sub> )		250 <sup>+0/-5</sup> °C	
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		20 - 40 seconds	
Ramp-down Rate		5°C/second max	
Time 25°C to peakTemperature (T <sub>P</sub> )		8 minutes max.	
Do not exceed		280°C	



## **Physical Specifications**

Terminal Material	Matte Tin-plated Axial leads
Lead Solderability	MIL-STD-750, Method 2026

## **Dimensions**



Dimensions in inches and (millimeters)

DO-41 SERIES

## **Environmental Specifications**

Operating/Storage Temperature	-40° C to ~ +150°C
Passive Aging	125° C, 1000 hours Meet Spec
Humidity Aging	+85°C, 85% R.H. 1000 hours Meet Spec
Thermal Shock	MIL-STD-202 Method 107G +85°C/-40°C 100 times Meet Spec
Solvent Resistance	MIL-STD-202, Method 215 No Change
Vibration	MIL-STD-883C, Method 2007.1, Condition A No Change